

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-34. (canceled)

35. (New) A process for producing an RFID label having an antenna and an oscillating circuit by using a printing process, comprising:
providing a printable substrate; and
applying at least part of at least one of the antenna and the oscillating circuit to the substrate by sheet-fed offset printing.

36. (New) The process of claim 35, wherein said step of applying comprises using a conductive paste or conductive ink to print conducting tracks as part of at least one of the antenna and the oscillating circuit.

37. (New) The process of claim 36, wherein the conductive ink is used and the conductive ink is an ink with metal particles.

38. (New) The process of claim 36, wherein the conductive paste is used and the conductive paste contains carbon black or carbon fibers.

39. (New) The process of claim 36, wherein said step of applying comprises applying the conductive paste or the conductive ink in a sheet-fed offset press with gripper transport.

40. (New) The process of claim 36 wherein said step of applying comprises applying the conductive paste or the conductive ink in a rotary web offset press.

41. (New) The process of claim 39, wherein said step of applying includes applying part of at least one of the antenna and the oscillating circuit to a rear surface of the substrate which is formed as a sheet, and flipping over the sheet in a turning device.

42. (New) The process of claim 35, further comprising the step of applying a protective varnish or protective ink to the substrate after part of at least one of the antenna and the oscillating circuit has been printed.

43. (New) The process of claim 42, wherein said step of applying a protective varnish or protective ink comprises transferring the protective varnish or protective ink to the substrate in a sheet-fed offset press.

44. (New) The process of claim 42, wherein said step of applying a protective varnish or protective ink comprises transferring the protective varnish to the substrate in a flexo press with an ink chamber blade and a screen roller.

45. (New) The process of claim 42, wherein said step of applying a protective varnish or protective ink comprises applying the protective varnish to the substrate in a flexo press with twin-roll capacity.

46. (New) A process for producing an RFID label having an antenna and an oscillating circuit using a printing process, comprising:

providing a printable substrate; and
applying at least part of at least one of the antenna and the oscillating circuit directly or indirectly to the substrate using a letterpress plate.

47. (New) The process of claim 46, further comprising clamping the letterpress plate onto a plate cylinder of a sheet-fed press or web-fed press, and transferring ink indirectly by way of a blanket cylinder to the substrate.

48. (New) The process of claim 46, wherein the letterpress plate arranged in a sheet-fed or web-fed press is in direct contact with the substrate.

49. (New) The process of claim 47, wherein the letterpress plate is used in a press which also contains offset printing units.

50. (New) The process of claim 35, wherein the substrate is a fibrous material.

51. (New) The process of claim 35, wherein the substrate is a film.

52. (New) The process of claim 35, wherein the substrate is a fabric of at least one of natural and synthetic fibers.

53. (New) The process of claim 35, further comprising, in the case of a substrate having absorbent properties, precoating, prevarnishing, or preprinting the substrate with a varnish or a pre-inking medium to reduce the absorbent properties.

54. (New) The process of claim 53, wherein the precoating, prevarnishing, or preprinting is effected by direct letterpress.

55. (New) The process of claim 53, wherein the precoating, prevarnishing, or preprinting is effected by a letterpress plate, acting indirectly by way of a blanket cylinder.

56. (New) The process of claim 53, wherein the precoating, prevarnishing, or preprinting is effected by a printing unit in an offset press.

57. (New) The process of claim 35, wherein said step of applying further comprises the steps of printing two lines with different length next to each other over a certain portion of their length, and connecting the two lines to each other at ends of a shorter line of the two lines to produce a capacitive element.

58. (New) The process of claim 35, wherein said step of applying further comprises the steps of printing a base line, printing an insulator over part of the base line, and printing an opposing line to produce a capacitive element .

59. (New) The process of claim 46, wherein the substrate is a fibrous material.

60. (New) The process of claim 46, wherein the substrate is a film.

61. (New) The process of claim 46, wherein the substrate is a fabric of at least one of natural and synthetic fibers.

62. (New) The process of claim 46, further comprising, in the case of a substrate having absorbent properties, precoating, prevarnishing, or preprinting the substrate with a varnish or a pre-inking medium to reduce the absorbent properties.

63. (New) The process of claim 62, wherein the precoating, prevarnishing, or preprinting is effected by direct letterpress.

64. (New) The process of claim 62, wherein the precoating, prevarnishing, or preprinting is effected by a letterpress plate, acting indirectly by way of a blanket cylinder.

65. (New) The process of claim 62, wherein the precoating, prevarnishing, or preprinting is effected by a printing unit in an offset press.

66. (New) The process of claim 46, wherein said step of applying further comprises the steps of printing two lines with different length next to each other over a certain portion of their length, and connecting the two lines to each other at ends of a shorter line of the two lines to produce a capacitive element.

67. (New) The process of claim 46, wherein said step of applying further comprises the steps of printing a base line, printing an insulator over part of the base line, and printing an opposing line to produce a capacitive element.

68. (New) The process of claim 35, wherein the step of applying comprises applying several copies of the at least part of at least one of the antenna and the oscillating circuit to the substrate which is formed as a sheet.

69. (New) The process of claim 35, wherein the step of applying comprises applying several copies of the at least part of at least one of the antenna and the oscillating circuit to the substrate which is formed as a sheet, each copy being used for a respective package or respective part of a package.

70. (New) The process of claim 35, wherein the step of applying comprises applying several copies of the at least part of at least one of the antenna and the oscillating circuit to the substrate which is formed as a sheet, each copy being intended for a single RFID label.

71. (New) The process of claim 68, further comprising the step of separating the copies on the substrate from each other.

72. (New) The process of claim 71, wherein the copies on the substrate are separated from each other in blocks.

73. (New) The process of claim 71, wherein the copies on the substrate are separated individually from each other.

74. (New) The process of claim 71, further comprising the steps of uniformly orienting the separated copies or blocks of copies, and applying the oscillating circuits, further parts of the oscillating circuits, or IC chips to the oriented copies or blocks of copies.

75. (New) The process of claim 71, further comprising the steps of attaching the separated copies to packages, and applying the oscillating circuits, further parts of the oscillating circuits, or IC chips to the attached copies.

76. (New) The process of claim 75, wherein the step of applying the oscillating circuits, further parts of the oscillating circuits, or IC chips to the attached copies is performed during a preparation of the packages in a folding box gluing machine.

77. (New) The process of claim 75, wherein the step of applying the oscillating circuits, further parts of the oscillating circuits, or IC chips to the copies is performed during a filling of the packages in a box-filling station.

78. (New) The process of claim 46, wherein the step of applying comprises applying several copies of the at least part of at least one of the antenna and the oscillating circuit to the substrate which is formed as a sheet.

79. (New) The process of claim 46, wherein the step of applying comprises applying several copies of the at least part of at least one of the antenna and the oscillating circuit to the substrate which is formed as a sheet, each copy being used for a respective package or respective part of a package.

80. (New) The process of claim 46, wherein the step of applying comprises applying several copies of the at least part of at least one of the antenna and the oscillating circuit to the substrate which is formed as a sheet, each copy being intended for a single RFID label.

81. (New) The process of claim 78, further comprising the step of separating the copies on the substrate from each other.

82. (New) The process of claim 81, wherein the copies on the substrate are separated from each other in blocks.

83. (New) The process of claim 81, wherein the copies on the substrate are separated individually from each other.

84. (New) The process of claim 81, further comprising the steps of uniformly orienting the separated copies or blocks of copies, and applying the oscillating circuits, further parts of the oscillating circuits, or IC chips to the oriented copies or blocks of copies.

85. (New) The process of claim 81, further comprising the steps of attaching the separated copies to packages, and applying the oscillating circuits, further parts of the oscillating circuits, or IC chips to the attached copies.

86. (New) The process of claim 85, wherein the step of applying the oscillating circuits, further parts of the oscillating circuits, or IC chips to the copies is performed during a preparation of the packages in a folding box gluing machine.

87. (New) The process of claim 85, wherein the step of applying the oscillating circuits, further parts of the oscillating circuits, or IC chips to the copies is performed during a filling of the packages in a box-filling station.